

1. General description

Standard reverse recovery power diode in a TO263 package.



2. Features and benefits

- Low forward voltage drop
- Low leakage current
- High voltage capability
- High inrush current capability

3. Applications

- Input rectifier
- Bypass diode

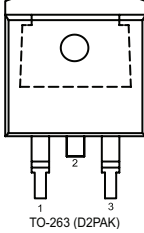
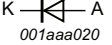
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
Absolute maximum rating						
V_{RRM}	repetitive peak reverse voltage		1200			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 97$ °C; Fig. 1 ; Fig. 2 ; Fig. 3	35			A
I_{FSM}	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; Fig. 4	400			A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse	435			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward voltage	$I_F = 35$ A; $T_j = 25$ °C; Fig. 6	-	1.18	1.40	V
		$I_F = 35$ A; $T_j = 150$ °C; Fig. 6	-	1.15	1.35	V

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode	 <p>TO-263 (D2PAK)</p>	 <p>001aaa020</p>
2	K	cathode [1]		
3	A	anode		
mb	K	mounting base; connected to cathode		

[1] It is not possible to connect to pin 2 of the TO263 package.

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WND35P12B	TO263	WND35P12BJ	Reel	800	TO263N	26-Sep-2016

7. Marking

Table 4. Marking codes

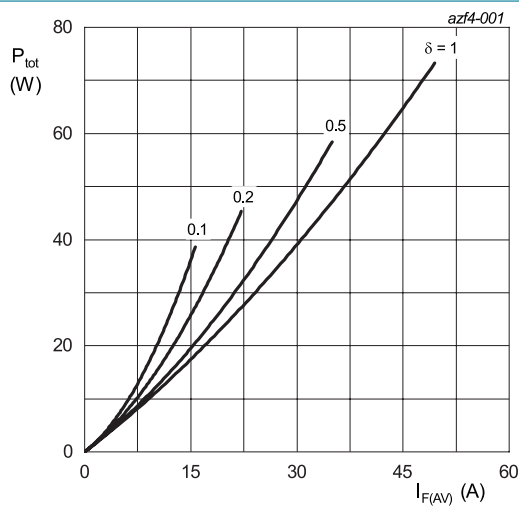
Type number	Marking codes
WND35P12B	WND35P12B

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

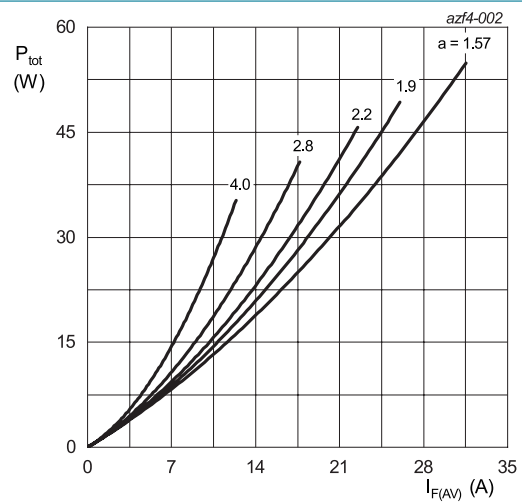
Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		1200	V
V_{RWM}	crest working reverse voltage		1200	V
V_R	reverse voltage	DC	1200	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 97\text{ }^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	35	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse; Fig. 4	400	A
		$t_p = 8.3\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse	435	A
T_{stg}	storage temperature		-40 to 150	$^\circ\text{C}$
T_j	junction temperature		-40 to 150	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.025\text{ V}; R_s = 0.0092\ \Omega$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 1.025\text{ V}; R_s = 0.0092\ \Omega$$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

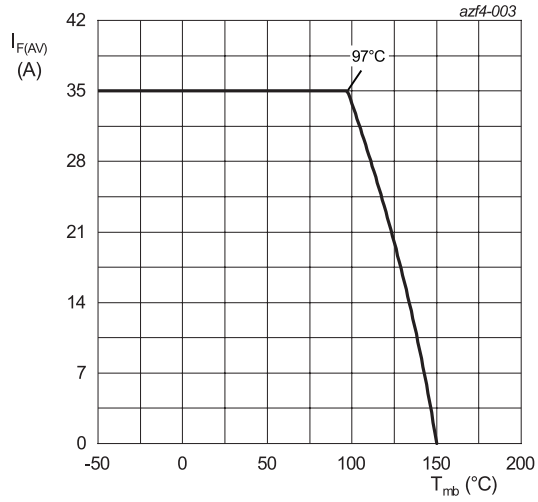


Fig. 3. Forward current as a function of mounting base temperature; maximum values

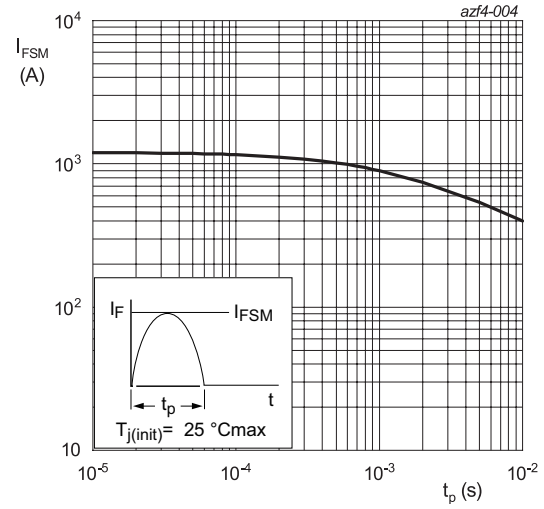


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	-	0.9	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	50	-	K/W

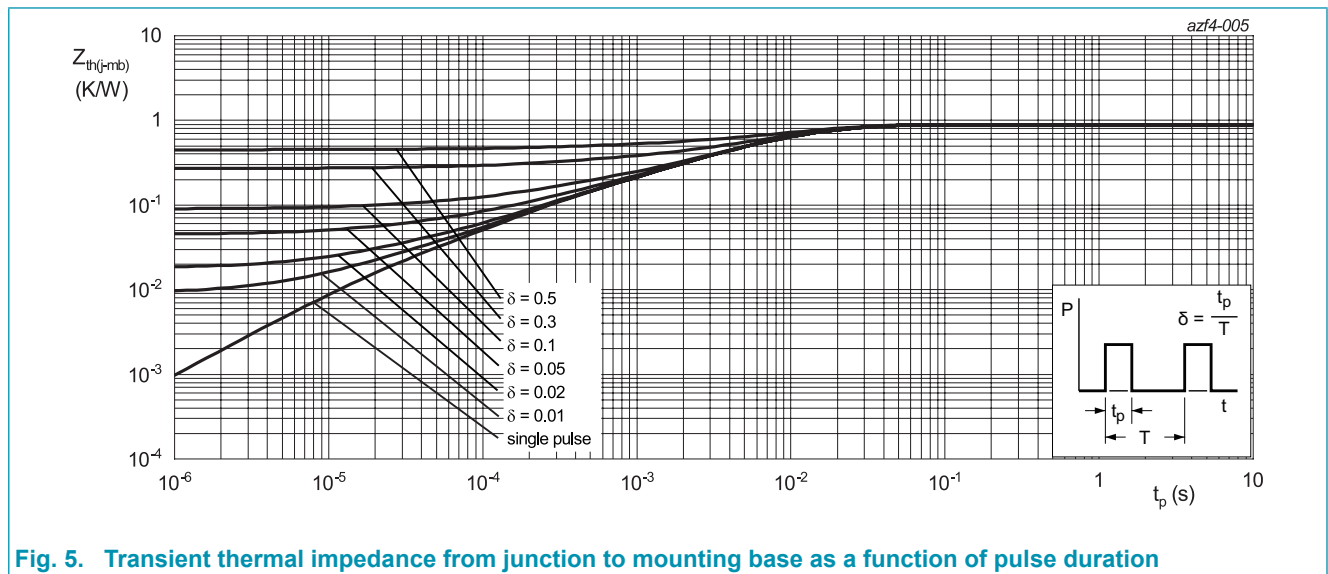
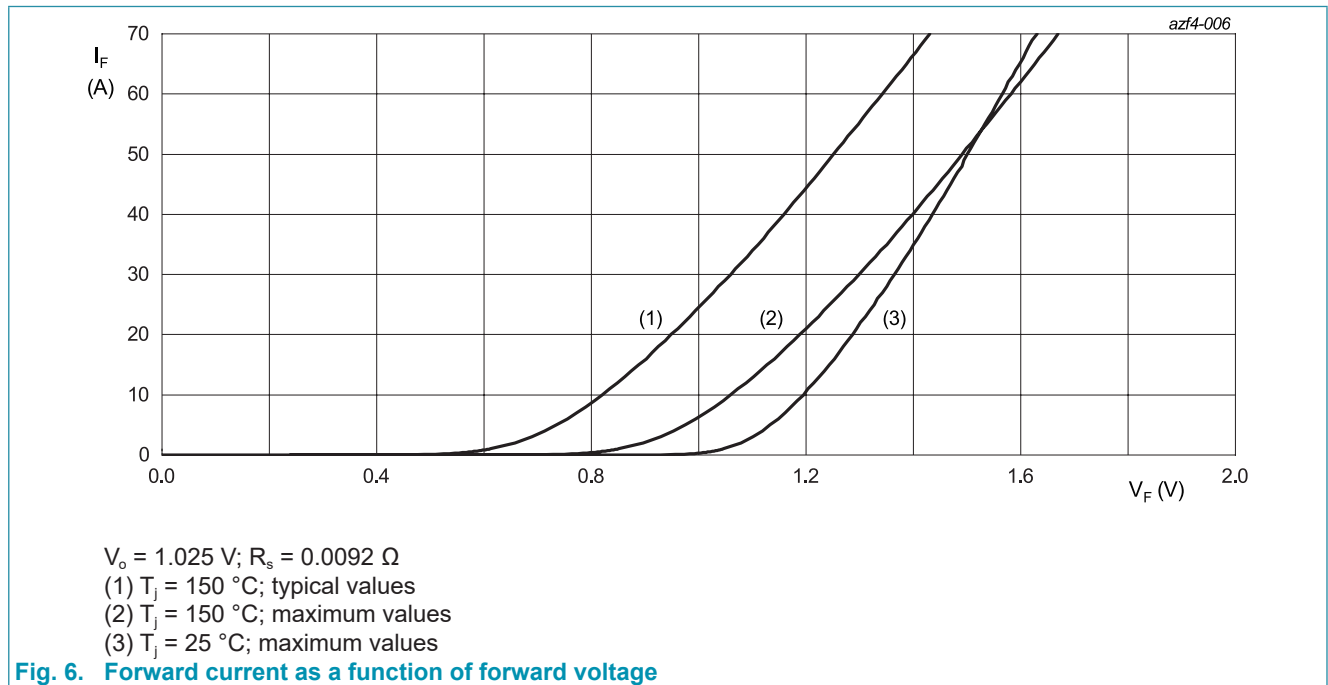


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

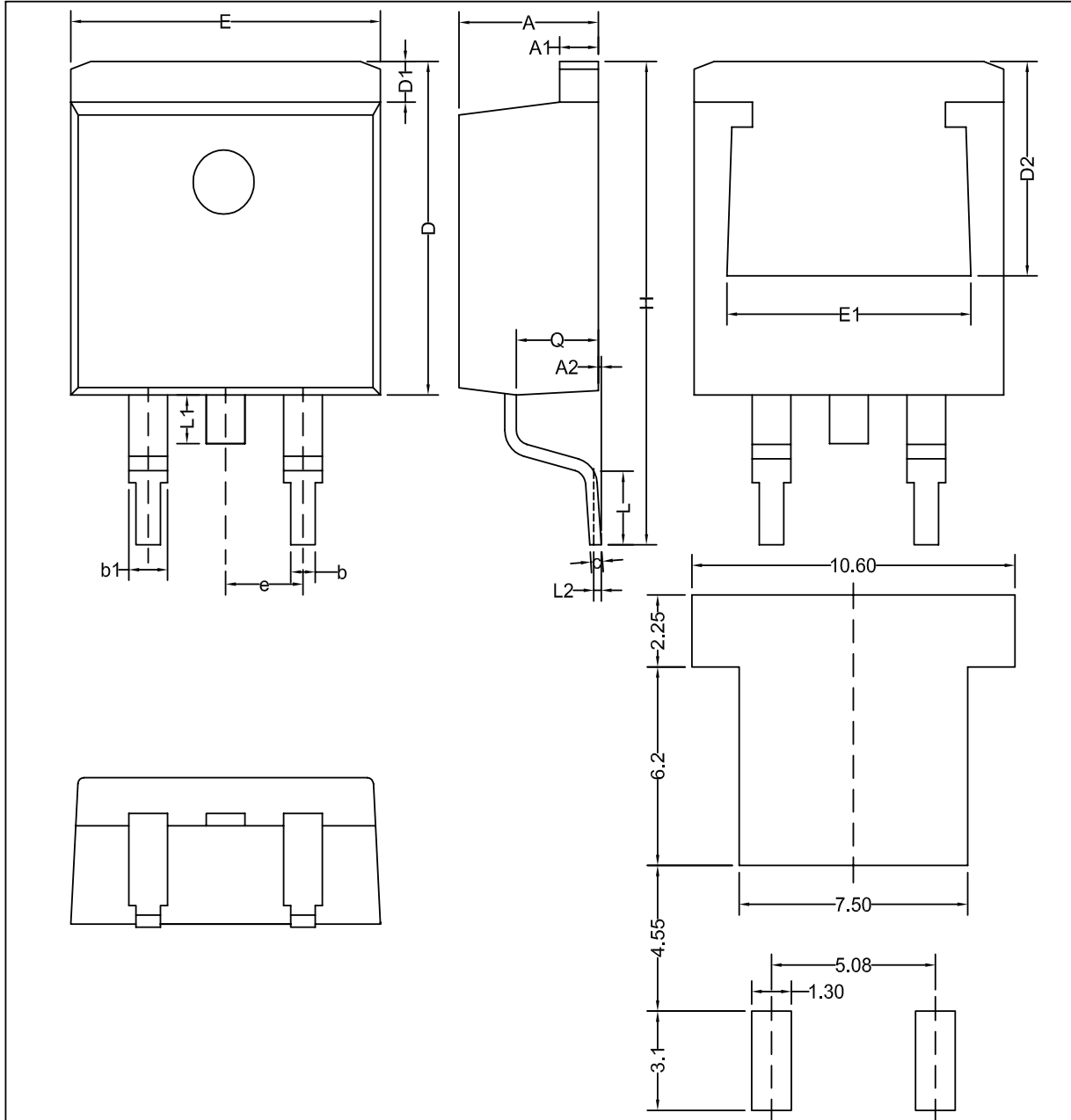
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward current	$I_F = 35\text{ A}; T_J = 25\text{ °C}; \text{Fig. 6}$	-	1.18	1.40	V
		$I_F = 35\text{ A}; T_J = 150\text{ °C}; \text{Fig. 6}$	-	1.15	1.35	V
		$I_F = 25\text{ A}; T_J = 25\text{ °C}; \text{Fig. 6}$	-	1.10	1.30	V
		$I_F = 25\text{ A}; T_J = 150\text{ °C}; \text{Fig. 6}$	-	1.05	1.25	V
I_R	reverse current	$V_R = 1200\text{ V}; T_J = 25\text{ °C}$	-	-	50	μA
		$V_R = 1200\text{ V}; T_J = 150\text{ °C}$	-	-	1	mA



11. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) TO263



Recommended Footprint

Unit	A	A1	A2	b	b1	c	D	D1	D2	e	E	E1	H	L	L1	L2	Q
min	4.10	1.22	0.00	0.60	1.05	0.34	---	1.20	6.60	2.54 (BSC)	9.70	7.80	14.80	2.10	---	0.25 (BSC)	2.20
max	4.70	1.40	0.25	0.90	1.45	0.64	11.00	1.60	---	---	10.30	---	15.80	2.90	1.75	---	2.79

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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